

Material Declaration Report



Part Number:	PI2EQX3202ANBE
Package Type:	LFBGA 84L
Pericom Package Code:	NB84 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
Date of RoHS Compliant:	Since Inception

Component Weight (mg):	213.200
Termination Plating:	SnAgCu
JESD 97 Pb-free Category:	e1
Plating Thickness (um):	N/A
Tin Whisker Mitigation:	N/A

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Date:	3/4/2008

Homogeneous Material Declaration

ITEM	MATERIAL WEIGHT(mg)	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	83.184	Silica fused	60676-86-0	84.000	69.8747
		Epoxy Resin	Proprietary	7.000	5.8229
		Phenol Resin	Proprietary	2.500	2.0796
		Metal Hydroxide	Proprietary	2.500	2.0796
		Carbon Black	1333-86-4	4.000	3.3274
SUBSTRATE	69.774	Gold	7440-57-5	0.670	0.4675
		Nickel	7440-02-0	29.070	20.2833
		Continuous Filament Fiber Glass	65997-17-3	7.350	5.1284
		Copper	7440-50-8	51.010	35.5917
		Bismaleimide /Triazine	13676-54-5 / 25722-66-1	0.920	0.6419
		Epoxy Resin	29690-82-2 / 68541-56-0 / 25068-38-6	6.430	4.4865
		Inorganic Filler	13776-74-4 / 7631-86-9	0.920	0.6419
		Morpholine derivative	Trade secret	3.630	2.5328
SILICON DIE	3.810	Silicon (Si)	7440-21-3	99.192	3.7791
		Non-hazardous Metal	Proprietary	0.808	0.0308
DIE ATTACH EPOXY	2.494	Silver	7440-22-4	80.000	1.9955
		Polymeric Resin	Proprietary	3.000	0.0748
		Diester Resin	Proprietary	10.000	0.2494
		Acrylate Resin	Proprietary	7.000	0.1746
GOLD WIRE	1.075	Gold(Au)	7440-57-93	99.990	1.0744
		Impurities	-	0.010	0.0001
SOLDER BALL	52.861	Tin(Sn)	7440-31-5	96.500	51.0107
		Silver(Ag)	7440-22-4	3.000	1.5858
		Copper(Cu)	7440-50-8	0.500	0.2643

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Substrate	<2	<2	<2	<2	<5	<5
Device	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Ball	<95	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table> <p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													